



STEIF POWER
TECHNOLOGY

20V N-Channel MOSFETs

SPEB2310Y

General Description

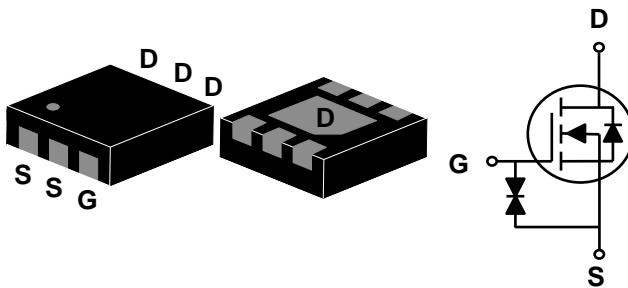
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDS(ON)	ID
20V	10mΩ	11A

Features

- 20V, 11A, RDS(ON) = 10mΩ @ VGS = 10V
- Improved dv/dt capability
- ESD Protection Diode Embedded
- Green Device Available

DFN2x2 6L Pin Configuration



Applications

- MB / VGA / Vcore
- POL Applications
- SMPS 2nd SR
- Li-Battery Protection



Absolute Maximum Ratings Tc=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
Vds	Drain-Source Voltage	20	V
Vgs	Gate-Source Voltage	±10	V
I _D	Drain Current – Continuous (T _c =25°C) (Chip Limitation)	11	A
	Drain Current – Continuous (T _c =100°C) (Chip Limitation)	6.9	A
I _{DM}	Drain Current – Pulsed ¹ (Chip Limitation)	44	A
P _D	Power Dissipation (T _c =25°C)	2.08	W
	Power Dissipation – Derate above 25°C	0.016	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to ambient	---	62	°C/W



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Electrical Characteristics ($T_J=25\text{ }^{\circ}\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	20	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to $25\text{ }^{\circ}\text{C}$, $I_D=1\text{mA}$	---	0.02	---	$\text{V}/^{\circ}\text{C}$
I_{DS}	Drain-Source Leakage Current	$V_{DS}=20\text{V}$, $V_{GS}=0\text{V}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	μA
		$V_{DS}=16\text{V}$, $V_{GS}=0\text{V}$, $T_J=125\text{ }^{\circ}\text{C}$	---	---	10	μA
I_{GS}	Gate-Source Leakage Current	$V_{GS}=\pm 10\text{V}$, $V_{DS}=0\text{V}$	---	---	± 10	μA

On Characteristics

$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS}=4.5\text{V}$, $I_D=5\text{A}$	---	8	10	$\text{m}\Omega$
		$V_{GS}=2.5\text{V}$, $I_D=3\text{A}$	---	9.5	12	$\text{m}\Omega$
		$V_{GS}=1.8\text{V}$, $I_D=2\text{A}$	---	12	17	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D = 250\mu\text{A}$	0.3	0.6	1	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	2	---	$\text{mV}/^{\circ}\text{C}$
g_{fs}	Forward Transconductance	$V_{DS}=10\text{V}$, $I_S=5\text{A}$	---	12	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{2,3}	$V_{DS}=10\text{V}$, $V_{GS}=4.5\text{V}$, $I_D=5\text{A}$	---	16.9	26	nC
Q_{gs}	Gate-Source Charge ^{2,3}		---	1.1	3	
Q_{gd}	Gate-Drain Charge ^{2,3}		---	4	7	
$T_{d(on)}$	Turn-On Delay Time ^{2,3}	$V_{DD}=10\text{V}$, $V_{GS}=4.5\text{V}$, $R_G=25\Omega$ $I_D=1\text{A}$	---	6.8	13	ns
T_r	Rise Time ^{2,3}		---	20	38	
$T_{d(off)}$	Turn-Off Delay Time ^{2,3}		---	41.8	79	
T_f	Fall Time ^{2,3}		---	13.2	25	
C_{iss}	Input Capacitance		---	1020	1480	pF
C_{oss}	Output Capacitance	$V_{DS}=10\text{V}$, $V_{GS}=0\text{V}$, $F=1\text{MHz}$	---	160	240	
C_{rss}	Reverse Transfer Capacitance		---	110	160	
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $F=1\text{MHz}$	---	2	4	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	11	A
I_{SM}	Pulsed Source Current		---	---	22	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=1\text{A}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.



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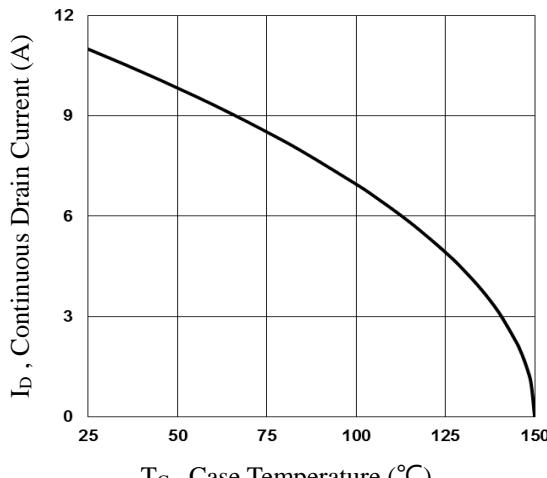


Fig.1 Continuous Drain Current vs. T_c

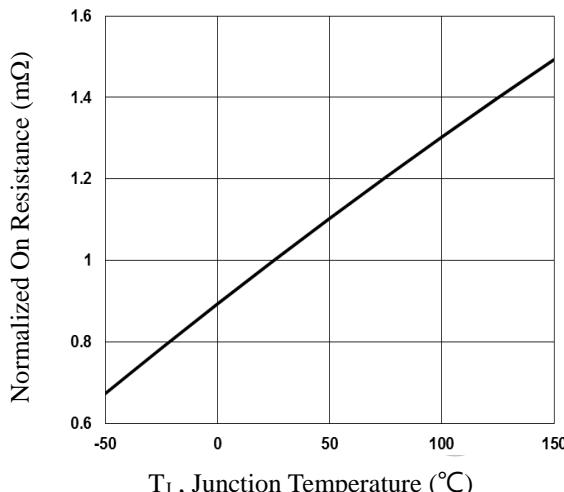


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

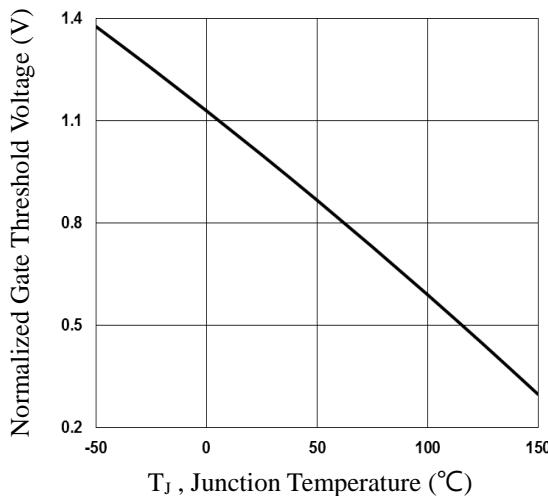


Fig.3 Normalized V_{th} vs. T_J

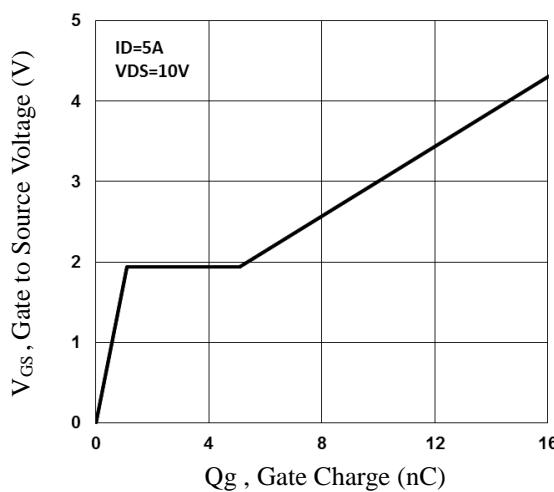


Fig.4 Gate Charge Waveform

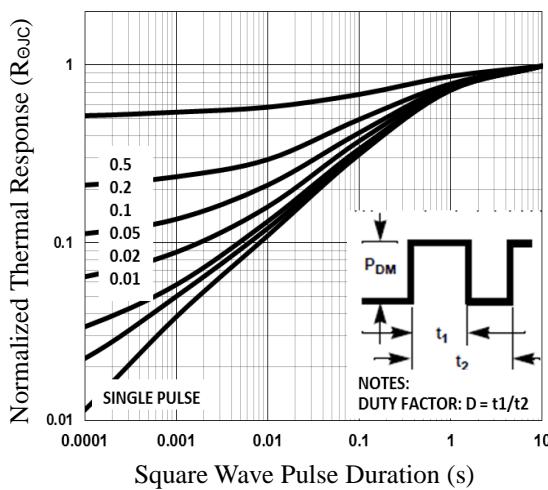


Fig.5 Normalized Transient Response

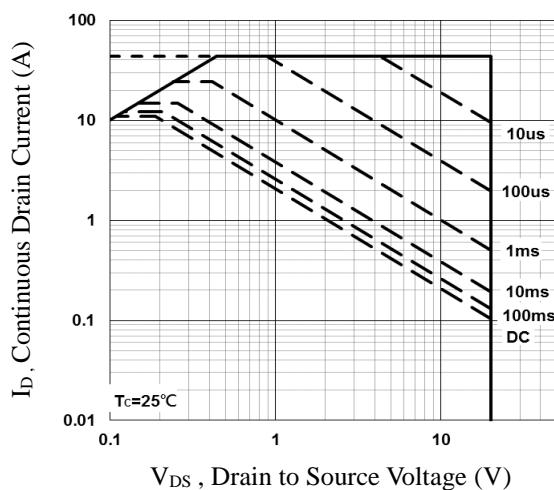


Fig.6 Maximum Safe Operation Area



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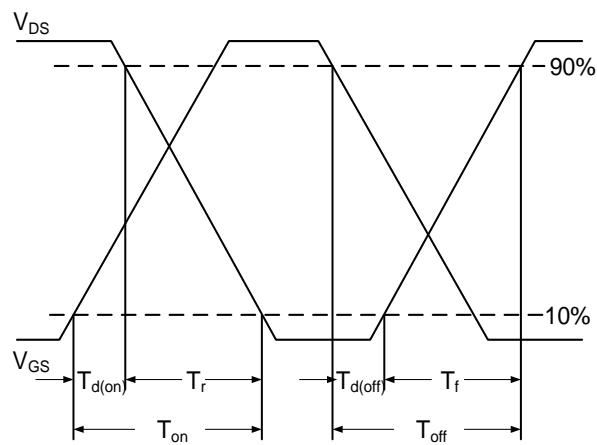


Fig.7 Switching Time Waveform

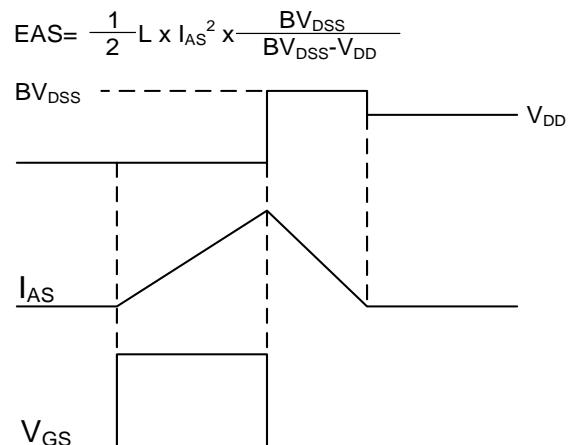


Fig.8 EAS Waveform

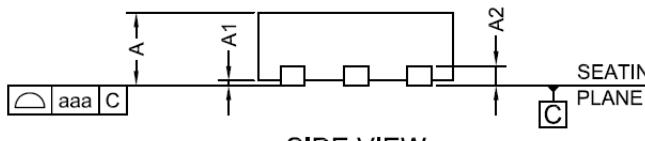


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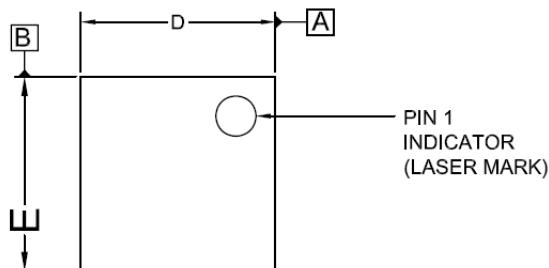
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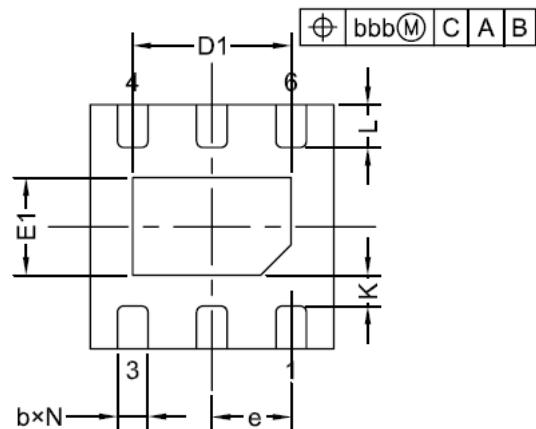
DFN2X2 6L PACKAGE INFORMATION



SIDE VIEW



TOP VIEW



BOTTOM VIEW

Symbol	Dimensions In Millimeters		
A	0.07	0.75	0.80
A1	0.00	0.02	0.05
A2		0.203	
b	0.20	0.25	0.30
D	1.95	2.00	2.05
D1	1.20	1.30	1.40
E	1.95	2.00	2.05
E1	0.70	0.80	0.90
e		0.65BSC	
L	0.30	0.35	0.40
K		0.20MIN	
N		6	
aaa		0.08	
bbb		0.10	